

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	140	divakaruni near ramachandra.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:53
L2	0	gluschenkow near oleg.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:54
L3	79	gluschenkov near oleg.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:54
L4	1	kwon near oh-jung.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:55
L5	24	malik near rajeev.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:56
L6	794	438/652.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:56
L7	9	6 and (array) near (region or area)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:58
L8	17592	(array) near (region or area)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:59
L9	206	(array) near (region or area) with (support) near (area or region)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 14:59

L10	61	9 and metal with polysilicon	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:00
L11	40	10 and (remov\$3) with (polysilicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:08
L12	4	10 and (remov\$3) with (thick near3 polysilicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:09
L13	4	9 and (remov\$3) with (thick near3 polysilicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:10
L14	73	9 and (remov\$3) with (polysilicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:10
L15	61	14 and metal	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:27
L16	1329	(thick) near (polysilicon or poly-silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:28
L17	3878	(thin) near (polysilicon or poly-silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:28
L18	7517	(thin) near3 (polysilicon or poly-silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:28
L19	2947	(thick) near3 (polysilicon or poly-silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:28

L20	773	18 and 19	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:28
L21	0	20 and (remov\$3) near3 (thick near3 poly\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:30
L22	683	20 and (remov\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:29
L23	0	9 and 22	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:29
L24	2	20 and (pattern\$3) near3 (thick near3 poly\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:34
L25	4	20 and (etch\$3) near3 (thick near3 poly\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:36
L26	1188	(memory near array) with (logic near circuit\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:39
L27	7	9 and 26	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:37
L28	7	27 and (polysilicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:37
L29	20925	(memory) with (logic near circuit\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:39

L30	155	18 and 29	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:40
L31	2	30 and (remov\$3) near3 (thick)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:47
L32	141	30 and (remov\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:46
L33	127	32 and (metal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:46
L34	74	30 and (remov\$3 or pattern\$3 or etch\$3) near5 (polysilicon or poly-silicon or poly near silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:48
L35	64	30 and (remov\$3 or pattern\$3 or etch\$3) near3 (polysilicon or poly-silicon or poly near silicon)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:48
L36	9	30 and (remov\$3 or pattern\$3 or etch\$3) near3 (polysilicon or poly-silicon or poly near silicon) with (metal)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/07/20 15:48